

Title (en)

Chip varistor for use in printed circuits, and method of producing it.

Title (de)

Varistor in Chip-Bauweise zur Verwendung in gedruckten Schaltungen und Verfahren zu seiner Herstellung.

Title (fr)

Varistance en forme de chip pour application dans les circuits imprimés et son procédé de fabrication.

Publication

EP 0171642 A1 19860219 (DE)

Application

EP 85109001 A 19850718

Priority

DE 3428242 A 19840731

Abstract (en)

1. A chip varistor for use in printed circuits (GS) for installation on conductor path contact surfaces (10, 11) of a printed circuit board (12), consisting of a parallelepiped-shaped ceramic body (20) of varistor material which is provided on oppositely disposed surfaces with solderable metal coatings (23, 24) as electrodes which extend at least on to that surface of the ceramic body (20) which faces towards the printed circuit board (12), characterized in that, at least on its side facing towards the printed circuit board (12), the ceramic body (20) is provided with a recess (25, 26) which forms two lateral parts (27, 28, 31, 32), that parts (35, 36, 37, 38) of the metal coatings (23, 24) extend to the end faces (29, 30, 33, 34) of the lateral parts (27, 28, 31, 32), and that the width and depth of the recess (25, 26) are such that the current path (41) along the surface parts of the recess (25, 26) between the ends (39, 40) of the parts (35, 36, 37, 38) of the metal coatings on the end faces (29, 30, 33, 34) of the lateral parts (27, 28, 31, 32) is longer than the lateral spacing (42) between the metal coatings (23, 24), which corresponds to the thickness of the ceramic body (20).

Abstract (de)

Es wird ein Varistor in Chip-Bauweise zur Verwendung in gedruckten Schaltungen vorgeschlagen, der aus einem quaderförmigen Keramikkörper (20) aus Varistormaterial besteht und wenigstens auf seiner der Schaltungsplatte (12) zugewandten Seite mit einer Einsenkung (25, 26) versehen ist, die zwei Seitenteile (27, 28, 31, 32) bildet, wobei Teile (35, 36, 37, 38) der Metallbelegungen (23, 24) auf die Stirnflächen (29, 30, 33, 34) der Seitenteile reichen und Breite und Tiefe der Einsenkung (25, 26) so bemessen sind, daß der Stromweg (41) längs der Oberflächenteile der Einsenkung (25, 26) zwischen den Enden (39, 40) der Metallbelegungen länger ist als der der Dicke des Keramikkörpers (20) entsprechende Abstand (42) zwischen den Metallbelegungen (23, 24)

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H01C 7/10

IPC 8 full level

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CPC (source: EP)

H01C 7/102 (2013.01)

Citation (search report)

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- [A] FR 2513032 A1 19830318 - CARRERAS MICHELLE [FR]

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